## DATA SHEET



## GaAs INTEGRATED CIRCUIT

# $\mu$ PG168TB

## L, S-BAND SPDT SWITCH

#### **DESCRIPTION**

The  $\mu$ PG168TB is GaAs MMIC for L, S-band SPDT (Single Pole Double Throw) switch which were developed for mobile phone and another L, S-band application.

This device can operate frequency from 0.5 to 2.5 GHz, having the low insertion loss and high isolation.

This device is housed in a 6-pin super minimold package. And this package is able to high-density surface mounting.

## **FEATURES**

Switch control voltage : Vcont (H) = 2.5 to 5.3 V (3.0 V TYP.)

:  $V_{cont(L)} = -0.2 \text{ to } +0.2 \text{ V } (0 \text{ V TYP.})$ 

• Low insertion loss : Lins1 = 0.30 dB TYP. @ f = 0.5 to 1.0 GHz,  $V_{cont}$  = 3.0 V/0 V

: Lins<sub>2</sub> = 0.40 dB TYP. @ f = 2.0 GHz,  $V_{cont}$  = 3.0 V/0 V

: LINS3 = 0.90 dB MAX. @ f = 2.0 to 2.5 GHz,  $V_{\text{cont}} = 3.0 \text{ V/0 V}$ 

• High isolation : ISL1 = 27 dB TYP. @ f = 0.5 to 2.0 GHz,  $V_{cont} = 3.0 \text{ V/O V}$ 

: ISL2 = 18 dB MIN. @ f = 2.0 to 2.5 GHz,  $V_{cont} = 3.0$  V/0 V

Middle power
 : Pin (1 dB) = +26.5 dBm TYP. @ f = 1.0 GHz, Vcont = 3.0 V/0 V

High-density surface mounting: 6-pin super minimold package (2.0 x 1.25 x 0.9 mm)

#### **APPLICATIONS**

- · L-band digital cellular or cordless telephone
- PCS, W-LAN, WLL and Bluetooth<sup>™</sup> etc.

## ORDERING INFORMATION

Part Number	Package	Marking	Supplying Form
μPG168TB-E4	6-pin super minimold	G2T	<ul> <li>Embossed tape 8 mm wide</li> <li>Pin 1, 2, 3 face the perforation side of the tape</li> <li>Qty 3 kpcs/reel</li> </ul>

Remark To order evaluation samples, contact your nearby sales office.

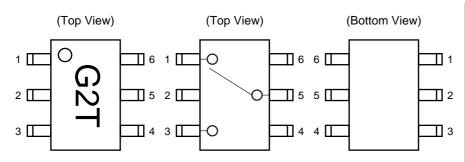
Part number for sample order:  $\mu$ PG168TB

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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## PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name	
1	OUTPUT2	
2	GND	
3	OUTPUT1	
4	V <sub>cont1</sub>	
5	INPUT	
6	V cont2	

## TRUTH TABLE

Vcont1	V <sub>cont2</sub>	INPUT-OUTPUT1	INPUT-OUTPUT2
Low	High	ON	OFF
High	Low	OFF	ON

## ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	Vcont	-6.0 to +6.0 Note1	V
Input Power	Pin	+28	dBm
Power Dissipation	Po	150 Note2	mW
Operating Ambient Temperature	TA	-45 to +85	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

**Note1.** Mounted on double-sided copper-clad  $50 \times 50 \times 1.6$  mm epoxy glass PWB,  $T_A = +85^{\circ}C$ 

**2.**  $|V_{cont1} - V_{cont2}| \le 6.0 \text{ V}$ 

## RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Switch Control Voltage (H)	V <sub>cont</sub> (H)	2.5	3.0	5.3	٧
Switch Control Voltage (L)	Vcont (L)	-0.2	0	0.2	V



#### **ELECTRICAL CHARACTERISTICS**

(TA = +25°C, V<sub>cont</sub> = 3.0 V/0 V, DC cut capacitors = 51 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	Lins1	f = 0.5 to 1.0 GHz	_	0.30	0.55	dB
Insertion Loss 2	LINS2	f = 2.0 GHz	-	0.40	0.65	dB
Insertion Loss 3	Lins3	f = 2.0 to 2.5 GHz	-	_	0.90	dB
Isolation 1	ISL1	f = 0.5 to 2.0 GHz	22	27	-	dB
Isolation 2	ISL2	f = 2.0 to 2.5 GHz	18	-	-	dB
Input Return Loss 1	RLin1	f = 0.5 to 2.0 GHz	13	19	-	dB
Input Return Loss 2	RLin2	f = 2.0 to 2.5 GHz	11	-	-	dB
Output Return Loss 1	RL <sub>out1</sub>	f = 0.5 to 2.0 GHz	13	19	-	dB
Output Return Loss 2	RL <sub>out2</sub>	f = 2.0 to 2.5 GHz	11	-	-	dB
1 dB Gain Compression Input Power Note	Pin (1 dB)	f = 1.0 GHz	+22.0	+26.5	-	dBm
Switch Control Speed	tsw		_	50	200	ns
Switch Control Current	Icont		_	0.5	10	μΑ

**Note** Pin (1 dB) is measured the input power level when the insertion loss increases more 1 dB than that of linear range.

#### STANDARD CHARACTERISTICS FOR REFERENCE

(TA = +25°C, V<sub>cont</sub> = 3.0 V/0 V, DC cut capacitors = 51 pF, unless otherwise specified)

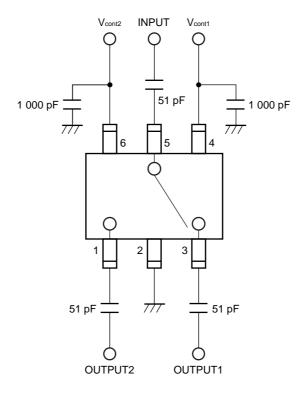
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
0.1 dB Gain Compression Input Power Note	Pin (0.1 dB)	f = 1.0 GHz	-	+23.0	-	dBm

**Note** Pin (0.1 dB) is measured the input power level when the insertion loss increases more 0.1 dB than that of linear range.

Caution This device is used it is necessary to use DC cut capacitors.

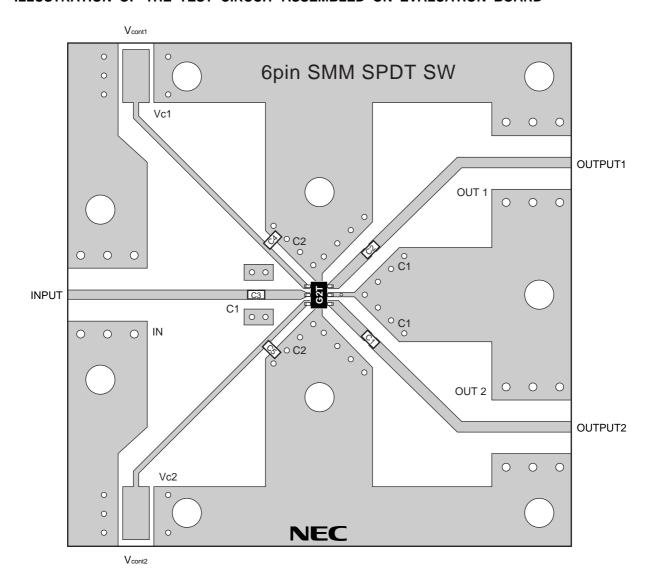
The value of DC cut capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system. The range of recommended DC cut capacitor value is less than 100 pF.

## **EVALUATION CIRCUIT (Vcont = 3.0 V/0 V, DC cut capacitors = 51 pF)**



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

## ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

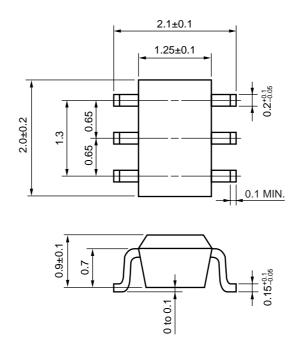


## USING THE NEC EVALUATION BOARD

Symbol	Values	
C1, C2, C3	51 pF	
C4, C5	1 000 pF	

## PACKAGE DIMENSIONS

## 6-PIN SUPER MINIMOLD (UNIT: mm)



## RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) Time at temperature of 200°C or higher Preheating time at 120 to 150°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 215°C or below : 25 to 40 seconds : 30 to 60 seconds : 3 times : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	H\$350

Caution Do not use different soldering methods together (except for partial heating).

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## SAFETY INFORMATION ON THIS PRODUCT

Caution

GaAs Products

The product contains gallium arsenide, GaAs.

GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not destroy or burn the product.
- Do not cut or cleave off any part of the product.
- Do not crush or chemically dissolve the product.
- Do not put the product in the mouth.

Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

#### ▶ For further information, please contact

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